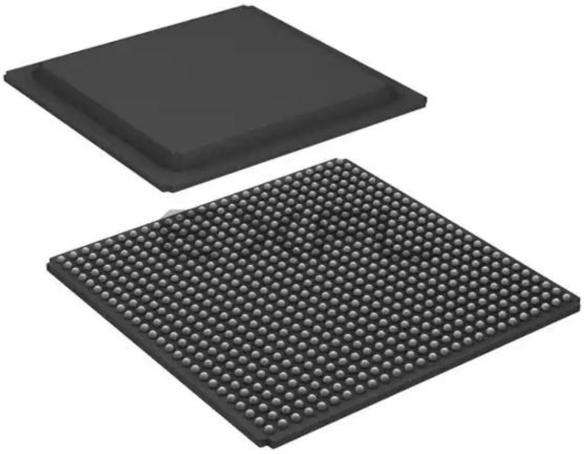
AMD Xilinx - XC2VP20-7FG676C Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	404
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-7fg676c

- HyperTransport (LDT) I/O with current driver buffers
- Built-in DDR input and output registers
- Proprietary high-performance SelectLink technology for communications between Xilinx devices
  - High-bandwidth data path
  - Double Data Rate (DDR) link
  - Web-based HDL generation methodology
- SRAM-Based In-System Configuration
  - Fast SelectMAP™ configuration
  - Triple Data Encryption Standard (DES) security option (bitstream encryption)
  - IEEE 1532 support
  - Partial reconfiguration
  - Unlimited reprogrammability
  - Readback capability
- Supported by Xilinx Foundation™ and Alliance Series™ Development Systems
  - Integrated VHDL and Verilog design flows
  - ChipScope™ Integrated Logic Analyzer
- 0.13 µm Nine-Layer Copper Process with 90 nm High-Speed Transistors
- 1.5V (V_{CCINT}) core power supply, dedicated 2.5V V_{CCAUX} auxiliary and V_{CCO} I/O power supplies
- IEEE 1149.1 Compatible Boundary-Scan Logic Support
- Flip-Chip and Wire-Bond Ball Grid Array (BGA) Packages in Standard 1.00 mm Pitch.
- Wire-Bond BGA Devices Available in Pb-Free Packaging (www.xilinx.com/pbfree)
- Each Device 100% Factory Tested

General Description

The Virtex-II Pro and Virtex-II Pro X families contain platform FPGAs for designs that are based on IP cores and customized modules. The family incorporates multi-gigabit transceivers and PowerPC CPU blocks in Virtex-II Pro Series FPGA architecture. It empowers complete solutions for telecommunication, wireless, networking, video, and DSP applications.

The leading-edge 0.13 µm CMOS nine-layer copper process and Virtex-II Pro architecture are optimized for high performance designs in a wide range of densities. Combining a wide variety of flexible features and IP cores, the Virtex-II Pro family enhances programmable logic design capabilities and is a powerful alternative to mask-programmed gate arrays.

Architecture

Array Overview

Virtex-II Pro and Virtex-II Pro X devices are user-programmable gate arrays with various configurable elements and embedded blocks optimized for high-density and high-performance system designs. Virtex-II Pro devices implement the following functionality:

- Embedded high-speed serial transceivers enable data bit rate up to 3.125 Gb/s per channel (RocketIO) or 6.25 Gb/s (RocketIO X).
- Embedded IBM PowerPC 405 RISC processor blocks provide performance up to 400 MHz.
- SelectIO-Ultra blocks provide the interface between package pins and the internal configurable logic. Most popular and leading-edge I/O standards are supported by the programmable IOBs.
- Configurable Logic Blocks (CLBs) provide functional elements for combinatorial and synchronous logic, including basic storage elements. BUFTs (3-state buffers) associated with each CLB element drive dedicated segmentable horizontal routing resources.
- Block SelectRAM+ memory modules provide large 18 Kb storage elements of True Dual-Port RAM.
- Embedded multiplier blocks are 18-bit x 18-bit dedicated multipliers.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for clock distribution delay compensation, clock multiplication and division, and coarse- and fine-grained clock phase shifting.

A new generation of programmable routing resources called Active Interconnect Technology interconnects all these elements. The general routing matrix (GRM) is an array of routing switches. Each programmable element is tied to a switch matrix, allowing multiple connections to the general routing matrix. The overall programmable interconnection is hierarchical and supports high-speed designs.

All programmable elements, including the routing resources, are controlled by values stored in static memory cells. These values are loaded in the memory cells during configuration and can be reloaded to change the functions of the programmable elements.

Features

This section briefly describes Virtex-II Pro / Virtex-II Pro X features. For more details, refer to Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description.

RocketIO / RocketIO X MGT Cores

The RocketIO and RocketIO X Multi-Gigabit Transceivers are flexible parallel-to-serial and serial-to-parallel embedded transceiver cores used for high-bandwidth interconnection between buses, backplanes, or other subsystems.

Multiple user instantiations in an FPGA are possible, providing up to 100 Gb/s (RocketIO) or 170 Gb/s (RocketIO X) of full-duplex raw data transfer. Each channel can be operated at a maximum data transfer rate of 3.125 Gb/s (RocketIO) or 6.25 Gb/s (RocketIO X).

cation is given at the receiver interface. The realignment indicator is a distinct output.

The transceiver continuously monitors the data for the presence of the 10-bit character(s). Upon each occurrence of a 10-bit character, the data is checked for word alignment. If comma detect is disabled, the data is not aligned to any particular pattern. The programmable option allows a user to align data on comma+, comma–, both, or a unique user-defined and programmed sequence.

Comma detection has been expanded beyond 10-bit symbol detection and alignment to include 8-bit symbol detection and alignment for 16-, 20-, 32-, and 40-bit paths. The ability to detect symbols, and then either align to 1-word, 2-word, or 4-word boundaries is included. The RXSLIDE input allows the user to “slide” or “slip” the alignment by one bit in each 16-, 20-, 32- and 40-bit mode at any time for SONET applications. Comma detection can be bypassed when needed.

Clock Correction

RXRECCLK (the recovered clock) reflects the data rate of the incoming data. RXUSRCLK defines the rate at which the FPGA fabric consumes the data. Ideally, these rates are identical. However, since the clocks typically have different sources, one of the clocks will be faster than the other. The receiver buffer accommodates this difference between the clock rates. See Figure 6.

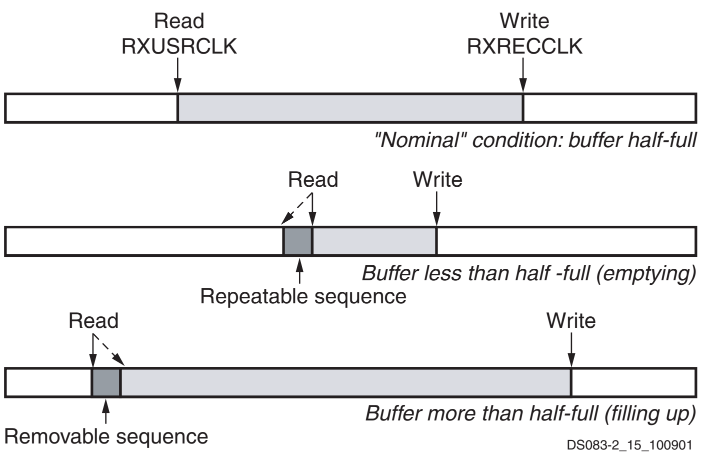


Figure 6: **Clock Correction in Receiver**

Nominally, the buffer is always half full. This is shown in the top buffer, Figure 6, where the shaded area represents buffered data not yet read. Received data is inserted via the write pointer under control of RXRECCLK. The FPGA fabric reads data via the read pointer under control of RXUSRCLK. The half full/half empty condition of the buffer gives a cushion for the differing clock rates. This operation continues indefinitely, regardless of whether or not "meaningful" data is being received. When there is no meaningful data to be received, the incoming data will consist of IDLE characters or other padding.

If RXUSRCLK is faster than RXRECCLK, the buffer becomes more empty over time. The clock correction logic corrects for this by decrementing the read pointer to reread a repeatable byte sequence. This is shown in the middle buffer, Figure 6, where the solid read pointer decrements to the value represented by the dashed pointer. By decrementing the read pointer instead of incrementing it in the usual fashion, the buffer is partially refilled. The transceiver design will repeat a single repeatable byte sequence when necessary to refill a buffer. If the byte sequence length is greater than one, and if attribute CLK_COR_REPEAT_WAIT is 0, then the transceiver may repeat the same sequence multiple times until the buffer is refilled to the desired extent.

Similarly, if RXUSRCLK is slower than RXRECCLK, the buffer will fill up over time. The clock correction logic corrects for this by incrementing the read pointer to skip over a removable byte sequence that need not appear in the final FPGA fabric byte stream. This is shown in the bottom buffer, Figure 6, where the solid read pointer increments to the value represented by the dashed pointer. This accelerates the emptying of the buffer, preventing its overflow. The transceiver design will skip a single byte sequence when necessary to partially empty a buffer. If attribute CLK_COR_REPEAT_WAIT is 0, the transceiver may also skip two consecutive removable byte sequences in one step to further empty the buffer when necessary.

These operations require the clock correction logic to recognize a byte sequence that can be freely repeated or omitted in the incoming data stream. This sequence is generally an IDLE sequence, or other sequence comprised of special values that occur in the gaps separating packets of meaningful data. These gaps are required to occur sufficiently often to facilitate the timely execution of clock correction.

Channel Bonding

Some gigabit I/O standards such as Infiniband specify the use of multiple transceivers in parallel for even higher data rates. Words of data are split into bytes, with each byte sent over a separate channel (transceiver). See Figure 7.

The top half of the figure shows the transmission of words split across four transceivers (channels or lanes). PPPP, QQQQ, RRRR, SSSS, and TTTT represent words sent over the four channels.

The bottom-left portion of Figure 7 shows the initial situation in the FPGA’s receivers at the other end of the four channels. Due to variations in transmission delay—especially if the channels are routed through repeaters—the FPGA fabric might not correctly assemble the bytes into complete words. The bottom-left illustration shows the incorrect assembly of data words PQPP, QRQQ, RSRR, and so forth.

To support correction of this misalignment, the data stream includes special byte sequences that define corresponding points in the several channels. In the bottom half of Figure 7, the shaded "P" bytes represent these special characters. Each receiver recognizes the "P" channel bond-

Table 5: **Clock Ratios for Various Data Widths**

Fabric Data Width	Frequency Ratio of USRCLK:USRCLK2
1-byte	1:2(1)
2-byte	1:1
4-byte	2:1(1)

Notes:
1. Each edge of slower clock must align with falling edge of faster clock.

FPGA Transmit Interface

The FPGA can send either one, two, or four characters of data to the transmitter. Each character can be either 8 bits or 10 bits wide. If 8-bit data is applied, the additional inputs become control signals for the 8B/10B encoder. When the 8B/10B encoder is bypassed, the 10-bit character order is generated as follows:

TXCHARDISPMODE[0] (first bit transmitted)
TXCHARDISPVAL[0]
TXDATA[7:0] (last bit transmitted is TXDATA[0])

Disparity Control

The 8B/10B encoder is initialized with a negative running disparity. Unique control allows forcing the current running disparity state.

TXRUNDISP signals its current running disparity. This may be useful in those cases where there is a need to manipulate the initial running disparity value.

Bits TXCHARDISPMODE and TXCHARDISPVAL control the generation of running disparity before each byte.

For example, the transceiver can generate the sequence

```
K28.5+ K28.5+ K28.5- K28.5-
```

or

```
K28.5- K28.5- K28.5+ K28.5+
```

by specifying inverted running disparity for the second and fourth bytes.

Transmit FIFO

Proper operation of the circuit is only possible if the FPGA clock (TXUSRCLK) is frequency-locked to the reference clock (REFCLK). Phase variations up to one clock cycle are allowable. The FIFO has a depth of four. Overflow or underflow conditions are detected and signaled at the interface. Bypassing of this FIFO is programmable.

8B/10B Encoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

A bypassable 8B/10B encoder is included. The encoder uses the same 256 data characters and 12 control characters used by Gigabit Ethernet, Fibre Channel, and InfiniBand.

The encoder accepts 8 bits of data along with a K-character signal for a total of 9 bits per character applied, and generates a 10 bit character for transmission. If the K-character signal is High, the data is encoded into one of the twelve possible K-characters available in the 8B/10B code. If the K-character input is Low, the 8 bits are encoded as standard data. If the K-character input is High, and a user applies other than one of the twelve possible combinations, TXKERR indicates the error.

8B/10B Decoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

An optional 8B/10B decoder is included. A programmable option allows the decoder to be bypassed. When the 8B/10B decoder is bypassed, the 10-bit character order is, for example,

RXCHARISK[0] (first bit received)
RXRUNDISP[0]
RXDATA[7:0] (last bit received is RXDATA[0])

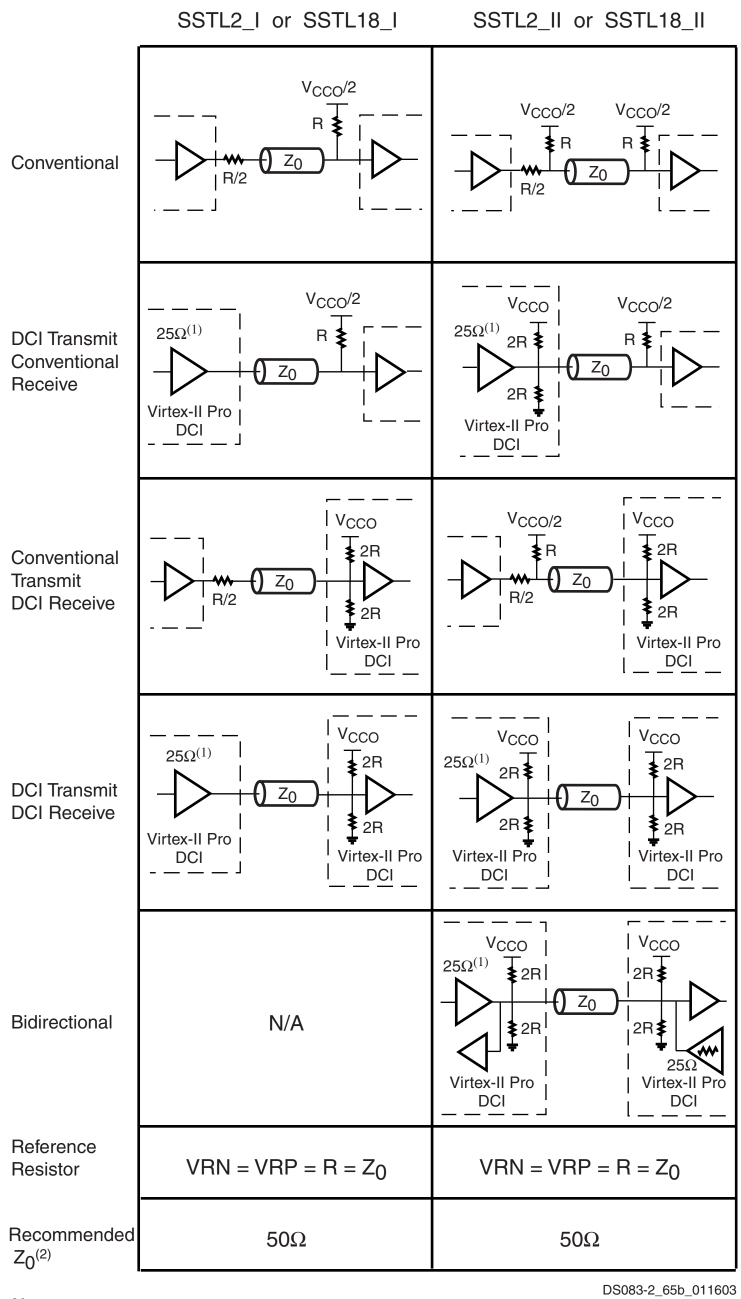
The decoder uses the same table that is used for Gigabit Ethernet, Fibre Channel, and InfiniBand. In addition to decoding all data and K-characters, the decoder has several extra features. The decoder separately detects both “disparity errors” and “out-of-band” errors. A disparity error is the reception of 10-bit character that exists within the 8B/10B table but has an incorrect disparity. An out-of-band error is the reception of a 10-bit character that does not exist within the 8B/10B table. It is possible to obtain an out-of-band error without having a disparity error. The proper disparity is always computed for both legal and illegal characters. The current running disparity is available at the RXRUNDISP signal.

The 8B/10B decoder performs a unique operation if out-of-band data is detected. If out-of-band data is detected, the decoder signals the error and passes the illegal 10-bits through and places them on the outputs. This can be used for debugging purposes if desired.

The decoder also signals the reception of one of the 12 valid K-characters. In addition, a programmable comma detect is included. The comma detect signal registers a comma on the receipt of any comma+, comma–, or both. Since the comma is defined as a 7-bit character, this includes several out-of-band characters. Another option allows the decoder to detect only the three defined commas (K28.1, K28.5, and K28.7) as comma+, comma–, or both. In total, there are six possible options, three for valid commas and three for "any comma."

Note that all bytes (1, 2, or 4) at the RX FPGA interface each have their own individual 8B/10B indicators (K-character, disparity error, out-of-band error, current running disparity, and comma detect).

Figure 29 provides examples illustrating the use of the SSTL2_I_DCI, SSTL2_II_DCI, SSTL18_I_DCI, and SSTL18_II_DCI I/O standards. For a complete list, see the ***Virtex-II Pro Platform FPGA User Guide***.



Notes:
1. The SSTL-compatible 25Ω series resistor is accounted for in the DCI buffer, and it is not DCI controlled.
2. Z_0 is the recommended PCB trace impedance.

Figure 29: **SSTL DCI Usage Examples**

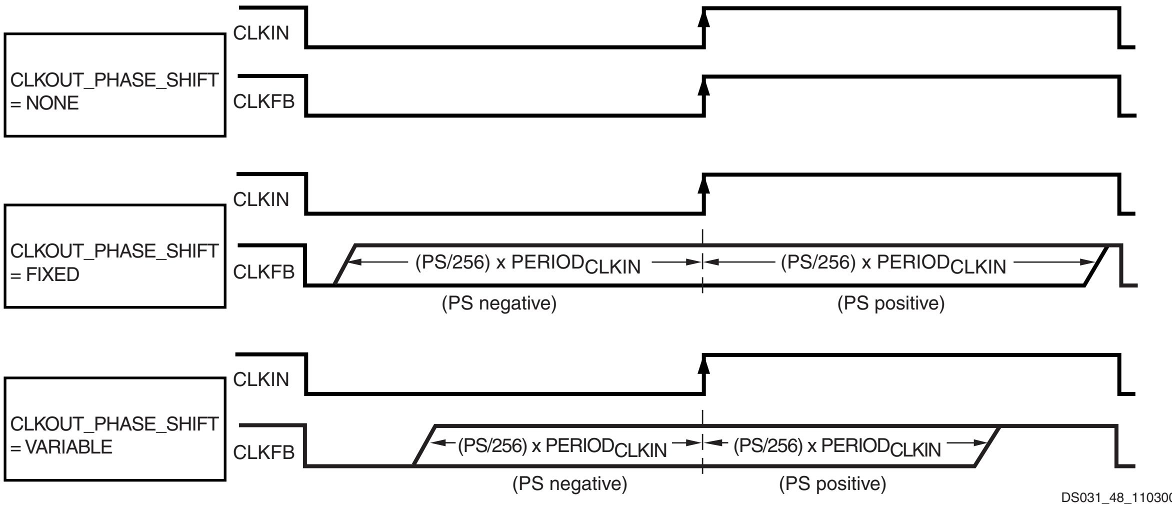


Figure 63: **Fine-Phase Shifting Effects**

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE\_SHIFT}/256) * \text{PERIOD}_{CLKIN}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If PERIOD_{CLKIN} = 2 * FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If PERIOD_{CLKIN} = FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $\text{PERIOD}_{CLKIN} \leq 0.5$ * FINE_SHIFT_RANGE, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 30. For actual values, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Input Clock Tolerances

Table 58: **Input Clock Tolerances**

Description	Symbol	Constraints F_{CLKIN}	Speed Grade –7 Min	–7 Max	–6 Min	–6 Max	–5 Min	–5 Max	Units
Input Clock Low/High Pulse Width									
PSCLK	PSCLK_PULSE	< 1MHz	25.00		25.00		25.00		ns
PSCLK and CLKIN(3)	PSCLK_PULSE and CLKIN_PULSE	1 – 10 MHz	25.00		25.00		25.00		ns
		10 – 25 MHz	10.00		10.00		10.00		ns
		25 – 50 MHz	5.00		5.00		5.00		ns
		50 – 100 MHz	3.00		3.00		3.00		ns
		100 – 150 MHz	2.40		2.40		2.40		ns
		150 – 200 MHz	2.00		2.00		2.00		ns
		200 – 250 MHz	1.80		1.80		1.80		ns
		250 – 300 MHz	1.50		1.50		1.50		ns
		300 – 350 MHz	1.30		1.30		1.30		ns
		350 – 400 MHz	1.15		1.15		1.15		ns
		> 400 MHz	1.05		1.05		1.05		ns
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_LF			±300		±300		±300	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_LF			±300		±300		±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_HF			±150		±150		±150	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_HF			±150		±150		±150	ps
Input Clock Period Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_LF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_LF			±1		±1		±1	ns
Input Clock Period Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_HF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_HF			±1		±1		±1	ns
Feedback Clock Path Delay Variation									
CLKFB off-chip feedback	CLKFB_DELAY_VAR_EXT			±1		±1		±1	ns

Notes:
1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If DCM phase shift feature is used and CLKIN frequency > 200 Mhz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VTRXPAD6	B9			
N/A	AVCCAUXRX6	B10			
N/A	AVCCAUXTX7	B14			
N/A	VTTXPAD7	B13			
N/A	TXNPAD7	A13			
N/A	TXPPAD7	A14			
N/A	GNDA7	C14			
N/A	RXPPAD7	A15			
N/A	RXNPAD7	A16			
N/A	VTRXPAD7	B15			
N/A	AVCCAUXRX7	B16			
N/A	AVCCAUXTX9	B18	NC	NC	
N/A	VTTXPAD9	B17	NC	NC	
N/A	TXNPAD9	A17	NC	NC	
N/A	TXPPAD9	A18	NC	NC	
N/A	GNDA9	C17	NC	NC	
N/A	RXPPAD9	A19	NC	NC	
N/A	RXNPAD9	A20	NC	NC	
N/A	VTRXPAD9	B19	NC	NC	
N/A	AVCCAUXRX9	B20	NC	NC	
N/A	AVCCAUXRX16	AA20	NC	NC	
N/A	VTRXPAD16	AA19	NC	NC	
N/A	RXNPAD16	AB20	NC	NC	
N/A	RXPPAD16	AB19	NC	NC	
N/A	GNDA16	Y17	NC	NC	
N/A	TXPPAD16	AB18	NC	NC	
N/A	TXNPAD16	AB17	NC	NC	
N/A	VTTXPAD16	AA17	NC	NC	
N/A	AVCCAUXTX16	AA18	NC	NC	
N/A	AVCCAUXRX18	AA16			
N/A	VTRXPAD18	AA15			
N/A	RXNPAD18	AB16			
N/A	RXPPAD18	AB15			
N/A	GNDA18	Y14			
N/A	TXPPAD18	AB14			
N/A	TXNPAD18	AB13			
N/A	VTTXPAD18	AA13			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L44P_7	G24	NC		
7	IO_L44N_7	G23	NC		
7	IO_L43P_7	G22	NC		
7	IO_L43N_7	G21	NC		
7	IO_L42P_7	F25	NC	NC	NC
7	IO_L42N_7	F24	NC	NC	NC
7	IO_L40P_7	F23	NC	NC	NC
7	IO_L40N_7/VREF_7	F22	NC	NC	NC
7	IO_L06P_7	E26			
7	IO_L06N_7	E25			
7	IO_L05P_7	E24			
7	IO_L05N_7	E23			
7	IO_L04P_7	D26			
7	IO_L04N_7/VREF_7	D25			
7	IO_L03P_7	C26			
7	IO_L03N_7	C25			
7	IO_L02P_7	B26			
7	IO_L02N_7	A25			
7	IO_L01P_7/VRN_7	D24			
7	IO_L01N_7/VRP_7	C23			
0	VCCO_0	C17			
0	VCCO_0	C20			
0	VCCO_0	H17			
0	VCCO_0	H18			
0	VCCO_0	J14			
0	VCCO_0	J15			
0	VCCO_0	J16			
1	VCCO_1	C7			
1	VCCO_1	H9			
1	VCCO_1	C10			
1	VCCO_1	H10			
1	VCCO_1	J11			
1	VCCO_1	J12			
1	VCCO_1	J13			
2	VCCO_2	G2			
2	VCCO_2	J8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	VCCINT		Y13			
N/A	VCCINT		Y12			
N/A	VCCINT		W20			
N/A	VCCINT		W11			
N/A	VCCINT		V20			
N/A	VCCINT		V11			
N/A	VCCINT		U20			
N/A	VCCINT		U11			
N/A	VCCINT		T20			
N/A	VCCINT		T11			
N/A	VCCINT		R20			
N/A	VCCINT		R11			
N/A	VCCINT		P20			
N/A	VCCINT		P11			
N/A	VCCINT		N20			
N/A	VCCINT		N11			
N/A	VCCINT		M20			
N/A	VCCINT		M11			
N/A	VCCINT		L19			
N/A	VCCINT		L18			
N/A	VCCINT		L17			
N/A	VCCINT		L16			
N/A	VCCINT		L15			
N/A	VCCINT		L14			
N/A	VCCINT		L13			
N/A	VCCINT		L12			
N/A	GND		AK22			
N/A	GND		AK9			
N/A	GND		AJ29			
N/A	GND		AJ2			
N/A	GND		AH28			
N/A	GND		AH17			
N/A	GND		AH14			
N/A	GND		AH3			
N/A	GND		AG27			
N/A	GND		AG22			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L01P_6/VRN_6	AJ30				
6	IO_L01N_6/VRP_6	AJ31				
6	IO_L02P_6	AJ27				
6	IO_L02N_6	AJ28				
6	IO_L03P_6	AK31				
6	IO_L03N_6/VREF_6	AK32				
6	IO_L04P_6	AH29				
6	IO_L04N_6	AH30				
6	IO_L05P_6	AH27				
6	IO_L05N_6	AG28				
6	IO_L06P_6	AL33				
6	IO_L06N_6	AL34				
6	IO_L15P_6	AG29	NC			
6	IO_L15N_6/VREF_6	AG30	NC			
6	IO_L16P_6	AK33	NC			
6	IO_L16N_6	AK34	NC			
6	IO_L17P_6	AF27	NC			
6	IO_L17N_6	AF28	NC			
6	IO_L18P_6	AJ33	NC			
6	IO_L18N_6	AJ34	NC			
6	IO_L19P_6	AH31	NC			
6	IO_L19N_6	AH32	NC			
6	IO_L20P_6	AD25	NC			
6	IO_L20N_6	AD26	NC			
6	IO_L21P_6	AG31	NC			
6	IO_L21N_6/VREF_6	AG32	NC			
6	IO_L22P_6	AF29	NC			
6	IO_L22N_6	AF30	NC			
6	IO_L23P_6	AE27	NC			
6	IO_L23N_6	AE28	NC			
6	IO_L24P_6	AH33	NC			
6	IO_L24N_6	AH34	NC			
6	IO_L31P_6	AF31				
6	IO_L31N_6	AF32				
6	IO_L32P_6	AC25				
6	IO_L32N_6	AC26				
6	IO_L33P_6	AG33				
6	IO_L33N_6/VREF_6	AG34				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L53P_6	W25				
6	IO_L53N_6	W26				
6	IO_L54P_6	AB33				
6	IO_L54N_6	AA33				
6	IO_L55P_6	Y28				
6	IO_L55N_6	Y29				
6	IO_L56P_6	W27				
6	IO_L56N_6	W28				
6	IO_L57P_6	Y31				
6	IO_L57N_6/VREF_6	Y32				
6	IO_L58P_6	W29				
6	IO_L58N_6	W30				
6	IO_L59P_6	W24				
6	IO_L59N_6	V24				
6	IO_L60P_6	AA34				
6	IO_L60N_6	Y34				
6	IO_L85P_6	W31				
6	IO_L85N_6	W32				
6	IO_L86P_6	V25				
6	IO_L86N_6	V26				
6	IO_L87P_6	Y33				
6	IO_L87N_6/VREF_6	W33				
6	IO_L88P_6	V29				
6	IO_L88N_6	V30				
6	IO_L89P_6	V27				
6	IO_L89N_6	V28				
6	IO_L90P_6	V31				
6	IO_L90N_6	V32				
7	IO_L90P_7	U32				
7	IO_L90N_7	U31				
7	IO_L89P_7	U28				
7	IO_L89N_7	U27				
7	IO_L88P_7	V33				
7	IO_L88N_7/VREF_7	U33				
7	IO_L87P_7	U30				
7	IO_L87N_7	U29				
7	IO_L86P_7	U26				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	IO_L86N_7	U25				
7	IO_L85P_7	T32				
7	IO_L85N_7	T31				
7	IO_L60P_7	T30				
7	IO_L60N_7	T29				
7	IO_L59P_7	T28				
7	IO_L59N_7	T27				
7	IO_L58P_7	T33				
7	IO_L58N_7/VREF_7	R33				
7	IO_L57P_7	R32				
7	IO_L57N_7	R31				
7	IO_L56P_7	T26				
7	IO_L56N_7	T25				
7	IO_L55P_7	R34				
7	IO_L55N_7	P34				
7	IO_L54P_7	R29				
7	IO_L54N_7	R28				
7	IO_L53P_7	U24				
7	IO_L53N_7	T24				
7	IO_L52P_7	P32				
7	IO_L52N_7/VREF_7	P31				
7	IO_L51P_7	P30				
7	IO_L51N_7	P29				
7	IO_L50P_7	R26				
7	IO_L50N_7	R25				
7	IO_L49P_7	P33				
7	IO_L49N_7	N33				
7	IO_L48P_7	N32				
7	IO_L48N_7	N31				
7	IO_L47P_7	P28				
7	IO_L47N_7	P27				
7	IO_L46P_7	N34				
7	IO_L46N_7/VREF_7	M34				
7	IO_L45P_7	N30				
7	IO_L45N_7	N29				
7	IO_L44P_7	P26				
7	IO_L44N_7	P25				
7	IO_L43P_7	M32				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L75N_1/GCLK3P	C17		
1	IO_L75P_1/GCLK2S	B17		
1	IO_L74N_1/GCLK1P	L17		
1	IO_L74P_1/GCLK0S	K17		
1	IO_L73N_1	E17		
1	IO_L73P_1	D17		
1	IO_L69N_1/VREF_1	G17		
1	IO_L69P_1	F17		
1	IO_L68N_1	J17		
1	IO_L68P_1	H17		
1	IO_L67N_1	C16		
1	IO_L67P_1	B16		
1	IO_L66N_1/VREF_1	G16	NC	
1	IO_L66P_1	F16	NC	
1	IO_L57N_1/VREF_1	B15		
1	IO_L57P_1	A15		
1	IO_L56N_1	L16		
1	IO_L56P_1	K16		
1	IO_L55N_1	D16		
1	IO_L55P_1	C15		
1	IO_L54N_1	F15		
1	IO_L54P_1	E15		
1	IO_L53_1/No_Pair	H16		
1	IO_L50_1/No_Pair	G15		
1	IO_L49N_1	B14		
1	IO_L49P_1	A14		
1	IO_L48N_1	D14		
1	IO_L48P_1	C14		
1	IO_L47N_1	L15		
1	IO_L47P_1	K15		
1	IO_L46N_1	F14		
1	IO_L46P_1	E14		
1	IO_L45N_1/VREF_1	H14		
1	IO_L45P_1	G14		
1	IO_L44N_1	L14		
1	IO_L44P_1	K14		
1	IO_L43N_1	C13		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L87N_6/VREF_6	V33		
6	IO_L88P_6	V30		
6	IO_L88N_6	V31		
6	IO_L89P_6	V24		
6	IO_L89N_6	V25		
6	IO_L90P_6	V28		
6	IO_L90N_6	V29		
7	IO_L90P_7	U32		
7	IO_L90N_7	V32		
7	IO_L89P_7	U28		
7	IO_L89N_7	U29		
7	IO_L88P_7	U30		
7	IO_L88N_7/VREF_7	U31		
7	IO_L87P_7	T33		
7	IO_L87N_7	U33		
7	IO_L86P_7	U26		
7	IO_L86N_7	U27		
7	IO_L85P_7	T31		
7	IO_L85N_7	T32		
7	IO_L60P_7	R33		
7	IO_L60N_7	R34		
7	IO_L59P_7	U24		
7	IO_L59N_7	U25		
7	IO_L58P_7	R29		
7	IO_L58N_7/VREF_7	R30		
7	IO_L57P_7	P33		
7	IO_L57N_7	P34		
7	IO_L56P_7	T28		
7	IO_L56N_7	T29		
7	IO_L55P_7	P32		
7	IO_L55N_7	R32		
7	IO_L54P_7	P29		
7	IO_L54N_7	P30		
7	IO_L53P_7	T24		
7	IO_L53N_7	T25		
7	IO_L52P_7	N32		
7	IO_L52N_7/VREF_7	N33		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
7	IO_L32P_7	N24		
7	IO_L32N_7	N25		
7	IO_L31P_7	G33		
7	IO_L31N_7	G34		
7	IO_L30P_7	H31		
7	IO_L30N_7	G32		
7	IO_L29P_7	N27		
7	IO_L29N_7	M28		
7	IO_L28P_7	G28		
7	IO_L28N_7/VREF_7	G29		
7	IO_L27P_7	F33		
7	IO_L27N_7	F34		
7	IO_L26P_7	M26		
7	IO_L26N_7	M27		
7	IO_L25P_7	F31		
7	IO_L25N_7	F32		
7	IO_L24P_7	F30		
7	IO_L24N_7	G30		
7	IO_L23P_7	L25		
7	IO_L23N_7	M25		
7	IO_L22P_7	F27		
7	IO_L22N_7/VREF_7	F28		
7	IO_L21P_7	E29		
7	IO_L21N_7	F29		
7	IO_L20P_7	L28		
7	IO_L20N_7	K28		
7	IO_L19P_7	D33		
7	IO_L19N_7	D34		
7	IO_L18P_7	D32		
7	IO_L18N_7	E32		
7	IO_L17P_7	K26		
7	IO_L17N_7	L26		
7	IO_L16P_7	D31		
7	IO_L16N_7/VREF_7	E31		
7	IO_L15P_7	D29		
7	IO_L15N_7	D30		
7	IO_L14P_7	J28		
7	IO_L14N_7	J29		

FF1517 Flip-Chip Fine-Pitch BGA Package

As shown in Table 12, XC2VP50 and XC2VP70 Virtex-II Pro devices are available in the FF1517 flip-chip fine-pitch BGA package. Following this table are the FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L01N_0/VRP_0	D31		
0	IO_L01P_0/VRN_0	E31		
0	IO_L02N_0	K30		
0	IO_L02P_0	J30		
0	IO_L03N_0	G30		
0	IO_L03P_0/VREF_0	H30		
0	IO_L05_0/No_Pair	K28		
0	IO_L06N_0	E30		
0	IO_L06P_0	F30		
0	IO_L07N_0	C30		
0	IO_L07P_0	D30		
0	IO_L08N_0	J29		
0	IO_L08P_0	K29		
0	IO_L09N_0	G29		
0	IO_L09P_0/VREF_0	H29		
0	IO_L19N_0	E29		
0	IO_L19P_0	F29		
0	IO_L20N_0	L28		
0	IO_L20P_0	L27		
0	IO_L21N_0	C29		
0	IO_L21P_0	D29		
0	IO_L25N_0	H28		
0	IO_L25P_0	J28		
0	IO_L26N_0	M27		
0	IO_L26P_0	M26		
0	IO_L27N_0	D28		
0	IO_L27P_0/VREF_0	E28		
0	IO_L28N_0	H27	NC	
0	IO_L28P_0	J27	NC	
0	IO_L29N_0	J26	NC	
0	IO_L29P_0	K26	NC	
0	IO_L30N_0	F28	NC	
0	IO_L30P_0	G27	NC	
0	IO_L34N_0	D27	NC	

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L35N_3		AH11		
3	IO_L35P_3		AH12		
3	IO_L34N_3		AH5		
3	IO_L34P_3		AH6		
3	IO_L33N_3/VREF_3		AH9		
3	IO_L33P_3		AH10		
3	IO_L32N_3		AJ11		
3	IO_L32P_3		AJ12		
3	IO_L31N_3		AJ1		
3	IO_L31P_3		AJ2		
3	IO_L30N_3		AJ5		
3	IO_L30P_3		AJ6		
3	IO_L29N_3		AJ9		
3	IO_L29P_3		AJ10		
3	IO_L28N_3		AJ7		
3	IO_L28P_3		AJ8		
3	IO_L27N_3/VREF_3		AK1		
3	IO_L27P_3		AK2		
3	IO_L26N_3		AK11		
3	IO_L26P_3		AK12		
3	IO_L25N_3		AK3		
3	IO_L25P_3		AK4		
3	IO_L24N_3		AK5		
3	IO_L24P_3		AK6		
3	IO_L23N_3		AK9		
3	IO_L23P_3		AK10		
3	IO_L22N_3		AK7		
3	IO_L22P_3		AK8		
3	IO_L21N_3/VREF_3		AL2		
3	IO_L21P_3		AL3		
3	IO_L20N_3		AL11		
3	IO_L20P_3		AL12		
3	IO_L19N_3		AL4		
3	IO_L19P_3		AL5		
3	IO_L18N_3		AL7		
3	IO_L18P_3		AL8		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	VCCO_2	F4	
1	VCCO_1	R21	
1	VCCO_1	P21	
1	VCCO_1	R20	
1	VCCO_1	P20	
1	VCCO_1	R19	
1	VCCO_1	P19	
1	VCCO_1	R18	
1	VCCO_1	P18	
1	VCCO_1	H18	
1	VCCO_1	D18	
1	VCCO_1	P17	
1	VCCO_1	H14	
1	VCCO_1	D14	
1	VCCO_1	M13	
1	VCCO_1	D10	
0	VCCO_0	D33	
0	VCCO_0	M30	
0	VCCO_0	H29	
0	VCCO_0	D29	
0	VCCO_0	P26	
0	VCCO_0	R25	
0	VCCO_0	P25	
0	VCCO_0	H25	
0	VCCO_0	D25	
0	VCCO_0	R24	
0	VCCO_0	P24	
0	VCCO_0	R23	
0	VCCO_0	P23	
0	VCCO_0	R22	
0	VCCO_0	P22	
N/A	CCLK	AM10	
N/A	PROG_B	J33	
N/A	DONE	AN10	
N/A	M0	AP33	
N/A	M1	AN33	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AD19	
N/A	GND	AC19	
N/A	GND	AB19	
N/A	GND	AA19	
N/A	GND	Y19	
N/A	GND	W19	
N/A	GND	V19	
N/A	GND	U19	
N/A	GND	M19	
N/A	GND	AF18	
N/A	GND	AE18	
N/A	GND	AD18	
N/A	GND	AC18	
N/A	GND	AB18	
N/A	GND	AA18	
N/A	GND	Y18	
N/A	GND	W18	
N/A	GND	V18	
N/A	GND	U18	
N/A	GND	BB17	
N/A	GND	AV17	
N/A	GND	AP17	
N/A	GND	AE17	
N/A	GND	AD17	
N/A	GND	AC17	
N/A	GND	AB17	
N/A	GND	AA17	
N/A	GND	Y17	
N/A	GND	W17	
N/A	GND	V17	
N/A	GND	J17	
N/A	GND	E17	
N/A	GND	A17	
N/A	GND	BB13	
N/A	GND	AV13	
N/A	GND	AP13	
N/A	GND	J13	

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
08/14/02	2.0	Added package and pinout information for new devices.
08/27/02	2.1	• Updated SelectIO-Ultra information in Table 4. (Table deleted in v2.3.) • Corrected direction for RXNPAD and TXPPAD in Table 4 (formerly Table 5).
09/27/02	2.2	Corrected Table 2 and Table 3 entries for XC2VP30, FF1152 package, maximum I/Os from 692 to 644.
11/20/02	2.3	Added Number of Differential Pairs data to Table 3. Removed former Table 4.
12/03/02	2.4	Corrections in Table 4: • Reclassified GCLKx (S/P) pins as Input/Output, since these pins can be used as normal I/Os if not used as clocks. • Added cautionary note to PWRDWN_B pin, indicating that this function is not supported.
01/20/03	2.5	Added and removed package/pinout information for existing devices: • In Table 1, added FG676 package information. • In Table 3, added FG676 package option for XC2VP20, XC2VP30, and XC2VP40. • In Table 12, removed FF1517 package option for XC2VP40. • Added FG676 package pinouts (Table 7) for XC2VP20, XC2VP30, and XC2VP40. • Added package diagram (Figure 3) for FG676 package.
05/19/03	2.5.1	• Added section **BREFCLK Pin Definitions**, page 5. • Added clarification to Table 4 and all device pinout tables regarding the dual-use nature of pins D0/DIN and BUSY/DOUT during configuration.
06/19/03	2.5.3	• Added notation of "open-drain" to TDO pin in Table 4. • The final GND pin in each of six pinout tables was inadvertently deleted in v2.5.1. This revision restores the deleted GND pins as follows: - Pin A1, Table 6, page 16 (FG456) - Pin AF26, Table 7, page 30 (FG676) - Pin AN34, Table 10, page 98 (FF1152) - Pin E1, Table 11, page 130 (FF1148) - Pin C38, Table 12, page 162 (FF1517) - Pin E1, Table 14, page 253 (FF1696)
08/25/03	2.5.5	• Table 4: Deleted Note 2, obsolete. There is only one GNDA pin per MGT. • Table 4: Deleted pins ALT_VRP and ALT_VRN. Not used in Virtex-II Pro FPGAs.
12/10/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to **Production status**.
02/19/04	3.1	• Table 4, signal descriptions column: - For signals TDI, TMS, and TCK, added: Pins are 3.3V-compatible. - For signals M2, M1, M0, added: Tie to 3.3V only with 100Ω series resistor. No toggling during or after configuration. - For signal TDO, added: No internal pull-up. External pull-up to 3.3V OK with resistor greater than 200Ω.
03/09/04	3.1.1	• Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
06/30/04	4.0	Merged in DS110-4 (Module 4 of Virtex-II Pro X data sheet). Added data on available Pb-free packages and updated package diagrams for affected devices.